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## \*\* CONTINUING DATA \*\*\*\*\*

This application is a CON of 10/031,000 01/16/2002 PAT 6,780,668  
 which is a 371 of PCT/JP00/04699 07/13/2000 *CME*

## \*\* FOREIGN APPLICATIONS \*\*\*\*\*

JAPAN 11-202847 07/16/1999  
 JAPAN 2000-63686 03/08/2000 *CME*

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

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Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR COUNTRY JAPAN	SHEETS DRAWING 35	TOTAL CLAIMS 10	INDEPENDENT CLAIMS 1
35 USC 119 (a-d) conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance	EXAMINER'S SIGNATURE <i>C. Kuehner</i>	INITIALS <i>CME</i>		
Verified and Acknowledged				

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## TITLE

Semiconductor device package manufacturing method and semiconductor device package manufactured by the method

☐ All Fees☐ 1.16 Fees ( Filing )